



AZUREWAVE Wi-Fi + BLUETOOTH MODULES WITH NXP SILICON

Selection Guide for IoT Applications



Part Number	AW-XM458	AW-CM276NF	AW-CM358	AW-AM457-D	AW-AM510	AW-NM191NF	AW-CU300 V2
Type Name	LGA	M.2 1216	LGA	LGA	LGA	M.2 1216	LGA
NXP Chipset	88W9098	88W8997	88W8987	IW416	IW416	88W8801	MW320
Wi-Fi®	 2x2 CDW DB (2.4/5 GHz)	 2x2 DB (2.4/5 GHz)	 1x1 DB (2.4/5 GHz)	 1x1 DB (2.4/5 GHz)	 1x1 DB (2.4/5 GHz)	 1x1 SB (2.4 GHz)	 1x1 SB (2.4 GHz)
Bluetooth®	5.3 BR/EDR/LE	5.3 BR/EDR/LE	5.2 BR/EDR/LE	5.2 BR/EDR/LE	5.2 BR/EDR/LE	No	No
Wi-Fi Host Interface	SDIO, PCIe	SDIO, PCIe	SDIO	SDIO	SDIO	SDIO	UART
Bluetooth Interface	UART	UART	UART	UART	UART	—	—
Dimensions (mm)	20 x 18 x 2.8	12 x 16 x 1.85	12 x 12 x 1.65	15 x 15 x 2.5	12 x 12 x 2.0	12 x 16 x 1.95	15 x 23 x 2.35
Certifications	CE, FCC, IC, Japan	CE, FCC, Japan, IC, AU/NZ, India, Mexico, NCC	CE, FCC, IC, Japan	CE, FCC, IC	CE, FCC, IC, Japan	CE, FCC, Japan	CE, FCC, NCC, IC, Brazil, China, Japan, Mexico, Argentina
Operating Temperature	-40 °C to 85 °C	-30 °C to 85 °C	-30 °C to 85 °C	0 °C to 70 °C	0 °C to 70 °C	-40 °C to 85 °C	-40 °C to 85 °C
Software Support	Linux® OS	Linux® OS, Android™ OS	RTOS, Linux® OS, Android™ OS	RTOS, Linux® OS	RTOS, Linux® OS	RTOS, Linux® OS	RTOS

www.nxp.com

NXP and the NXP logo are trademarks of NXP B.V. Android is a trademark of Google LLC. The Bluetooth® word mark and logos are registered trademarks owned by Bluetooth SIG, Inc. and any use of such marks by NXP Semiconductors is under license. All other product or service names are the property of their respective owners. © 2022 NXP B.V.